

## Title (en)

Use of micromodule as surface mount package and corresponding method

## Title (de)

Verwendung einer Mikromodul als oberflächenmontiertes Gehäuse und entsprechendes Verfahren

## Title (fr)

Utilisation d'un micromodule comme boîtier de montage en surface et procédé correspondant

## Publication

**EP 0746188 A1 19961204 (FR)**

## Application

**EP 96401143 A 19960528**

## Priority

FR 9506328 A 19950529

## Abstract (en)

The micromodule is made into an enclosure by combining a micromodule (M) with protruding connectors (6) formed as contact zones flush w.r.t. each other onto a semiconductor substrate (S) which has corresponding contact areas (5) and tracks. The tracks cover the substrate surface and have end holes for surface mounted pins to be connected to the substrate. Solder expansion barriers (4) are provided at each connector.

## Abstract (fr)

Un micromodule M est utilisé comme boîtier de montage en surface d'un substrat d'interconnexions S. Dans un premier mode de réalisation de l'invention, des barrières à l'expansion de soudure 4 sont formées entre des zones de contact 1 du micromodule et des plots de contact correspondants du substrat S. Une butée mécanique 6 est prévue pour maintenir l'épaisseur e de l'interface de soudure. Dans un autre mode de réalisation de l'invention, des zones de contact se prolongent par des languettes, une opération de cambrage permettant de former des broches B1 de montage en surface. <IMAGE>

## IPC 1-7

**H05K 3/34**; **H01L 23/498**

## IPC 8 full level

**H05K 1/18** (2006.01); **G06K 19/077** (2006.01); **H01L 23/24** (2006.01); **H01L 23/31** (2006.01); **H01L 23/498** (2006.01); **H05K 3/34** (2006.01)

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## C-Set (source: EP US)

1. **H01L 2224/48091** + **H01L 2924/00014**
2. **H01L 2224/97** + **H01L 2224/85**
3. **H01L 2924/00014** + **H01L 2224/45099**
4. **H01L 2924/181** + **H01L 2924/00012**

## Citation (search report)

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## Cited by

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